Thermal paste GD-3, 3g, 7.5 W/m K

Reference: AM6848
EAN13: -
HS code: 38249996

Product attributes:

Product features:

Color: Gray
Max. operating temperature: 120 °C
Thermal conductivity: 7.5 W/mK

Product description:

Thermally conductive paste GD-3 is designed to improve heat transfer between electronic components and heat sinks. It is used during assembly or servicing of processors, LED elements and other heat-stressed components, where it helps to fill microscopic irregularities between the contact surfaces.

Technical specifications

- Designation: GD-3
- Product type: thermal paste
- Packaging: syringe
- Color: gray
- Refill weight: 3 g
- Thermal conductivity: 7.5 W/m K
- Specific gravity: 2.5 g/cm3
- Operating temperature: -35 to +120 °C
- Intended use: for processors, LEDs and other components with heat dissipation requirements

Functions and features

- It serves as a thermally conductive interface between the component and the heat sink.
- The syringe design allows for more precise dosing during application.
- The gray paste is intended for application to the contact surfaces of cooled elements.
- Suitable for use in electronics and when mounting heat sinks on semiconductor elements.

Ideal for

- Processor installation and service.
- Applications with LED modules and LED coolers.
- Electronic components requiring heat transfer to a heat sink.
- Service and installation work in the field of electronics cooling.

Package contents

- 1x GD-3 thermal paste in a syringe, 3 g

Why choose this product?

- A clearly designated product for thermal connection between component and heat sink.
- Known thermal conductivity value given in the input documents.
- The syringe packaging facilitates controlled application.
- Suitable for service, maintenance and new installation of electronic devices.

Installation and operating instructions

- Clean and degrease both contact surfaces before application.
- Apply the paste in a thin, continuous layer only to the designated contact area.
- Excessive amounts may deteriorate the quality of the thermal bond and contaminate surrounding parts.
- After application, ensure proper pressure of the heat sink to the component.

Safety notice

- Use the product only to transfer heat between suitable contact surfaces.
- Avoid contact of the paste with connectors, contacts and other parts not intended for application.
- Do not apply to energized equipment.

- Keep out of reach of children.